



FQA46N15 / FQA46N15_F109 150V N-Channel MOSFET

Features

- 50A, 150V, $R_{DS(on)}$ = 0.042 Ω @V_{GS} = 10 V Low gate charge (typical 85 nC)
- Low Crss (typical 100pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating

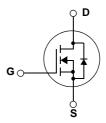


Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies, active power factor correction, electronic lamp ballast based on half bridge topology.





Absolute Maximum Ratings

Symbol	Parameter		FQA46N15	Units	
V _{DSS}	Drain-Source Voltage		150	V	
I _D	Drain Current - Continuous (T _C = 25°C)		50	Α	
	- Continuous (T _C = 100°C)	35.3	Α		
I _{DM}	Drain Current - Pulsed	(Note 1)	200	Α	
V _{GSS}	Gate-Source Voltage		± 25	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	650	mJ	
I _{AR}	Avalanche Current	(Note 1)	50	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	25	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)		6.0	V/ns	
P_{D}	Power Dissipation (T _C = 25°C)		250	W	
	- Derate above 25°C		1.67	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C	
T _L	Maximum lead temperature for soldering purposes 1/8" from case for 5 seconds	300	°C		

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.6	°C/W	
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQA46N15	FQA46N15	TO-3PN			30
FQA46N15	FQA46N15_F109	TO-3PN			30

Electrical Characteristics $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units		
Off Charac	Off Characteristics							
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_{D} = 250 μ A	150			V		
$\Delta BV_{DSS}/$ ΔT_J	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C		0.16		V/°C		
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 150 V, V _{GS} = 0 V			1	μА		
		V _{DS} = 120 V, T _C = 150°C			10	μΑ		
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V			100	nA		
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA		
On Charact	eristics							
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	V		
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 25A		0.033	0.042	Ω		
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 25A (Note 4)		36		S		
Dynamic Cl	Dynamic Characteristics							
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,		2500	3250	pF		
C _{oss}	Output Capacitance	f = 1.0 MHz		520	670	pF		
C _{rss}	Reverse Transfer Capacitance			100	130	pF		
Switching C	Switching Characteristics							
t _{d(on)}	Turn-On Delay Time	V _{DD} = 75 V, I _D = 45.6A,		35	80	ns		
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		320	650	ns		
t _{d(off)}	Turn-Off Delay Time	4) (4.5)		210	430	ns		
t _f	Turn-Off Fall Time	(Note 4, 5)		200	410	ns		
Qg	Total Gate Charge	V _{DS} = 120 V, I _D = 45.6A,		85	110	nC		
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		15		nC		
Q_{gd}	Gate-Drain Charge	(Note 4, 5)		41		nC		
Drain-Source	ce Diode Characteristics and Maximum Ratings	3						
I _S	Maximum Continuous Drain-Source Diode Forward Current				50	Α		
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				200	Α		
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S =50A			1.5	V		
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_S = 45.6 \text{ A},$		130		ns		
Q _{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note 4)		0.55		μС		

NOTES

^{1.} Repetitive Rating : Pulse width limited by maximum junction temperature

^{2.} L = 0.43mH, I_{AS} =50A, V_{DD} = 25V, R_G = 25 Ω , Starting T_J = 25°C

^{3.} $I_{SD} \le 45.6 A$, di/dt $\le 300 A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting T_J = 25°C

^{4.} Pulse Test : Pulse width $\leq 300 \mu \text{s}, \, \text{Duty cycle} \leq 2\%$

^{5.} Essentially independent of operating temperature

Typical Performance Characteristics

Figure 1. On-Region Characteristics

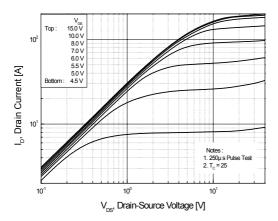


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

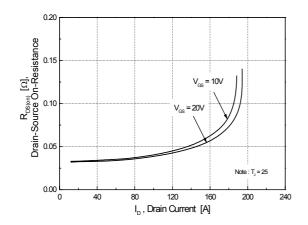


Figure 5. Capacitance Characteristics

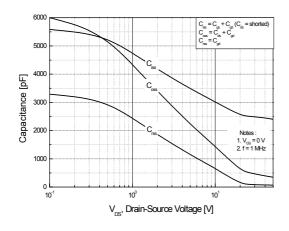


Figure 2. Transfer Characteristics

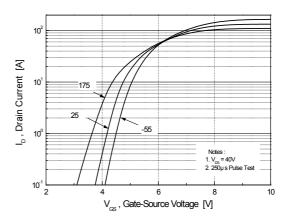


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

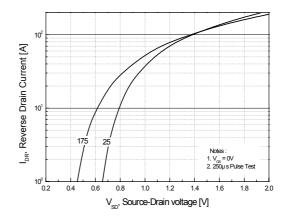
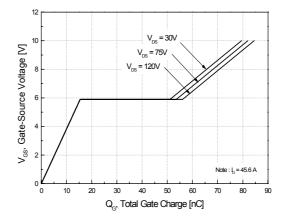


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

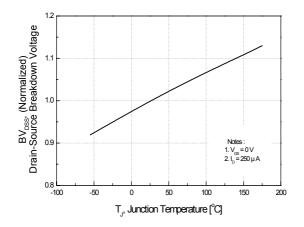


Figure 9. Maximum Safe Operating Area

Figure 8. On-Resistance Variation vs. Temperature

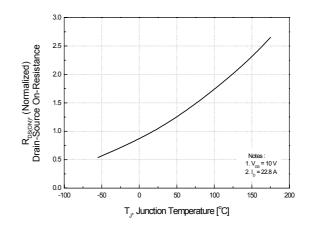


Figure 10. Maximum Drain Current vs. Case Temperature

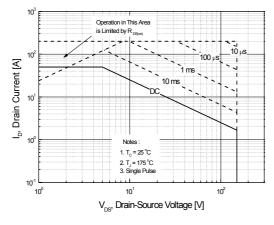
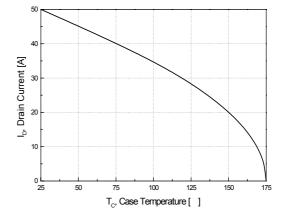
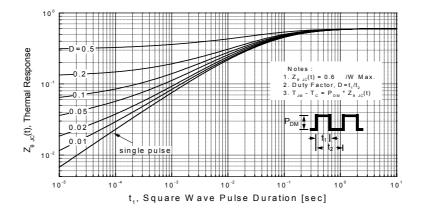
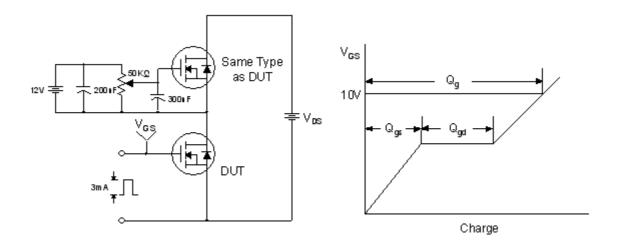


Figure 11. Transient Thermal Response Curve

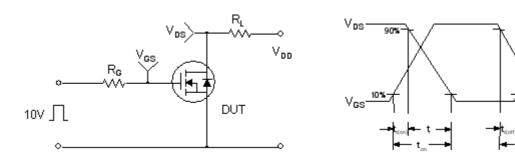




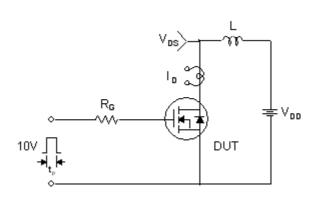
Gate Charge Test Circuit & Waveform

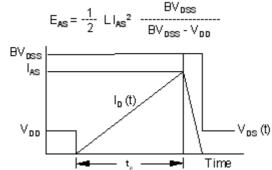


Resistive Switching Test Circuit & Waveforms

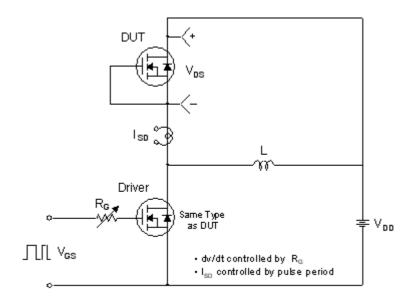


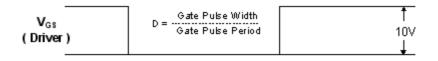
Unclamped Inductive Switching Test Circuit & Waveforms

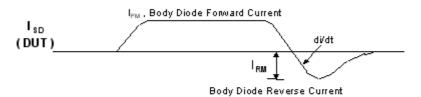


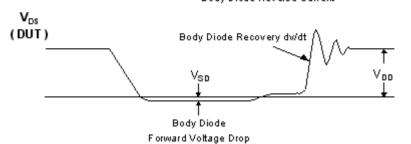


Peak Diode Recovery dv/dt Test Circuit & Waveforms



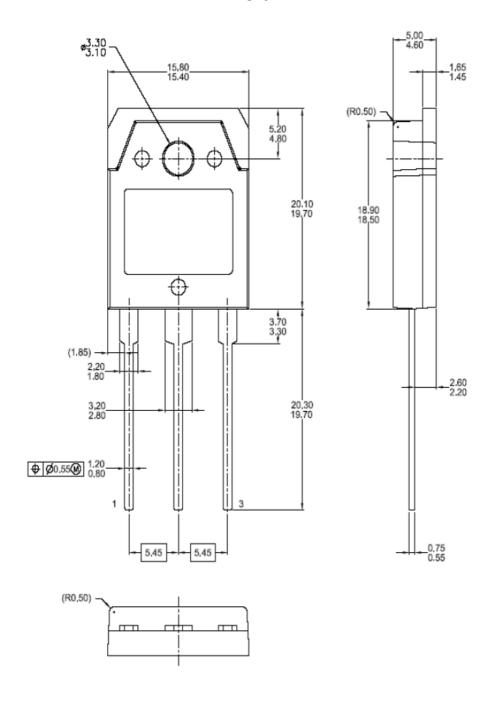






Mechanical Dimensions

TO-3PN



Dimensions in Millimeters





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